

Bill of Materials

TI DESIGNS

TIDA-00715

Item	Designator	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number
1	TIDA00715	1			Printed Circuit Board		TIDA00715
2	+Vs	1	Red Insulated Banana Jack		BANANA JACK, SOLDER LUG, RED, TH	Tenma	SPC15363
3	-Vs	1	Green Insulated Banana Jack		BANANA JACK, SOLDER LUG, GREEN, TH	Tenma	SPC15182
4	C1, C5	2	0603	0.1uF	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	TDK	C1608X7R1H104K
5	C11, C12, C13, C14	4	1206	0 ohm	RES, 0, 5%, 0.25 W, 1206	Vishay-Dale	CRCW12060000Z0EA
6	C15, C17, C19, C21	4	0603	1000pF	CAP, CERM, 1000 pF, 50 V, +/- 5%, COG/NPO, 0603	TDK	C1608C0G1H102J
7	C16, C18, C20, C22	4	0603	100pF	CAP, CERM, 100 pF, 50 V, +/- 5%, COG/NPO, 0603	AVX	06035A101JAT2A
8	C23, C25, C27, C29	4	0402	1000pF	CAP, CERM, 1000 pF, 25 V, +/- 5%, COG/NPO, 0402	TDK	C1005C0G1E102J
9	C24, C26, C28, C30	4	0402	100pF	CAP, CERM, 100 pF, 50 V, +/- 5%, COG/NPO, 0402	Yageo America	CC0402JRNPO9BN101
10	C39, C41	2	1206	10uF	CAP, CERM, 10 µF, 25 V, +/- 10%, X5R, 1206	MuRata	GRM31CR61E106KA12L
11	C40, C42	2	0805	0.1uF	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0805	AVX	08055C104KAT2A
12	GND	1	Black Insulated Banana Jack		BANANA JACK, SOLDER LUG, BLACK, TH	Tenma	SPC15354
13	H1, H2, H3, H4	4	Screw		Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	B&F Fastener Supply	NY PMS 440 0025 PH
14	H5, H6, H7, H8	4	Standoff		Standoff, Hex, 0.5"L #4-40 Nylon	Keystone	1902C
15	J8	1	Audio Jack SMD		Audio Jack, 3.5mm, Stereo, R/A, SMT	CUI Inc.	SJ-3523-SMT
16	L1, L2	2	1206	1.5uH	Inductor, Multilayer, Ferrite, 1.5 µH, 1 A, 0.17 ohm, SMD	MuRata	LQM31PN1R5MCOL
17	LBL1	1	PCB Label 0.650"H x 0.200"W		Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	Brady	THT-14-423-10
18	R1, R2, R3, R7, R9, R11, R21, R22, R25, R27, R29, R31	12	0603	1.10k	RES, 1.10 k, 0.1%, 0.1 W, 0603	Yageo America	RT0603BRD071K1L
19	R4, R5, R23, R24	4	0603	698	RES, 698, 0.1%, 0.1 W, 0603	Yageo America	RT0603BRD07698RL
20	R6, R8, R10, R12, R26, R28, R30, R32	8	0603	732	RES, 732, 0.1%, 0.1 W, 0603	Yageo America	RT0603BRD07732RL
21	R13, R14, R33, R34	4	0603	1.0	RES, 1.0, 5%, 0.1 W, 0603	Vishay-Dale	CRCW06031R00JNEA
22	R15, R37	2	1206	32.4	RES, 32.4, 1%, 0.25 W, 1206	Vishay-Dale	CRCW120632R4FKEA
23	R16, R17, R20, R38, R39, R40	6	0402	49.9	RES, 49.9, 1%, 0.063 W, 0402	Vishay-Dale	CRCW040249R9FKED
24	R18, R19, R35, R36	4	0603	0	RES, 0, 5%, 0.1 W, 0603	Vishay-Dale	CRCW06030000Z0EA
25	S1	1	SMD, 3-Leads, Body 8.5x3.5mm, Pitch 2.5mm		Switch, Slide, SPDT, 0.2A, GULL, 12V, SMD	Copal Electronics	CL-SB-12B-01T
26	U1, U3	2	DGK0008A		VERY LOW POWER, NEGATIVE RAIL INPUT, RAIL-TO-RAIL OUTPUT, FULLY DIFFERENTIAL AMPLIFIER, DGK0008A	Texas Instruments	THS4521IDGK

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27	U2, U4	2	RUN0010A		Dual, Very Low Power, Rail to Rail Out, Negative Rail In, VFB Operational Amplifier, 2.5 to 5.5 V, -40 to 85 degC, 10-pin QFN (RUN0010A), Green (RoHS & no Sb/Br)	Texas Instruments	OPA2836IRUNT
28	VF1, VF2, VF6, VF7, VF8, VF12	6	0.250 SQ	142-0711-821	CONNECTOR, SHEILDED, END LAUNCH JACK, GOLD PLATED, FOR 0.062 PCB, EDGE MOUNTED	Cinch Connectivity Solutions Johnson	142-0711-821
29	C2, C3, C4, C6, C7, C8, C9, C10	0	0402		CAP, CERM, xxxF, xxV, [TempCo], xx%, [PackageReference]	Used in BOM report	
30	FID1, FID2, FID3	0	Fiducial		Fiducial mark. There is nothing to buy or mount.	N/A	N/A
31	R41, R42, R43, R44	0	0603	1.11k	RES, 1.11 k, 0.1%, 0.1 W, 0603	Yageo America	RT0603BRD071K11L
32	R45, R46, R47, R48	0	0402	0	RES, 0, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04020000Z0ED
33	TPG1, TPG2, TPG3	0	Black Multipurpose Testpoint	Black	Test Point, Multipurpose, Black, TH	Keystone	5011
34	VF4, VF5, VF10, VF11	0	SMA		Connector, TH, SMA	Emerson Network Power	142-0701-201

Notes:

Unless otherwise noted in the Alternate PartNumber and/or Alternate Manufacturer columns, all parts may be substituted with equivalents.

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